

Initial Product/Process Change Notification

Document #:IPCN23823X Issue Date:09 Feb 2021

Title of Change:	Transfer OPN NLSX0102FCT1G / NLSX0102FCT2G / NLSX0102FC2T2G from FCI to JCET (turnkey for bump/FT/singulation/TnR.			
Proposed First Ship date:	31 Aug 2021 or earlier	31 Aug 2021 or earlier if approved by customer		
Contact Information:	Contact your local ON	Contact your local ON Semiconductor Sales Office or Doina.Patrascu@onsemi.com		
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>		
Type of Notification:	advance notification all change details and dev plan.The completed qu Product/Process Chang Product/Process Chang	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN. Support@onsemi.com>		
Marking of Parts/ Traceability of Change:	Traceability of change	Traceability of change will be on the datecode		
Change Category:	Assembly Change	Assembly Change		
Change Sub-Category(s):	Manufacturing Site Tra	Manufacturing Site Transfer		
Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		
None		JCET, China		

Description and Purpose:

There are no product material changes as a result of this change.

	Before Change Description	After Change Description	
Bump Location Change	Flipchip International-USA	JCET, China	
Laser Marking Location Change Flipchip International-USA		JCET, China	

Reason for Change: Transfer to new manufacturing location, to support short and long term demand. There is no product marking change as a result of this change.

TEM001790 Rev. C Page 1 of 2



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Qualification Plan:

QV DEVICE NAME: NLSX0102FCT1G

PACKAGE: Flip-Chip-8

Test	Specification	Condition	Interval
TC + PC	JESD22-A104	Ta= -40°C to +125°C	850 cycles
HAST + PC	JESD22-A110	130°C,85% RH,18.8psig,bias	96 hours
uHAST + PC	JESD22-A118	130°C,85% RH,18.8psig,unbiased	96 hours
PC	J-STD-020 JESD-A113	3x reflow @ 260C	
SD	JSTD002	Ta = 245C, 5sec	

Estimated date for qualification completion: 20 August 2021

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Part Number	Qualification Vehicle	
NLSX0102FCT1G	NLSX0102FCT1G	
NLSX0102FCT2G	NLSX0102FCT1G	
NLSX0102FC2T2G	NLSX0102FCT1G	

TEM001790 Rev. C Page 2 of 2



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NLSX0102FCT1G		NLSX0102FCT1G	NA	
NLSX0102FC2T2G		NLSX0102FCT1G	NA	
NLSX0102FCT2G		NLSX0102FCT1G	NA	